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# **2025 Operation Briefing of Nan Ya PCB Corp.**

**March 17<sup>th</sup> 2026**



# Disclaimer

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**The description of historical events might include the information that was not reviewed by accountants. Thus, it might be insufficient to fully exhibit the financial status or operation results of Nan Ya PCB Corp.**

**The actual operation results, financial status, and sales outlook in the future might be different from what will be indicated or implied in this meeting. The reasons may be including but not limited to the market demand, price fluctuation, competition dynamic, global economy, supply-chain, foreign exchange rate, and other risks that the Company cannot control.**

**Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.**



# Agenda

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- **Company Profile**
- **Financial Status**
- **Future Product Development**
- **Operational Strategies in 2026**



# Company Profile

## Business Overview

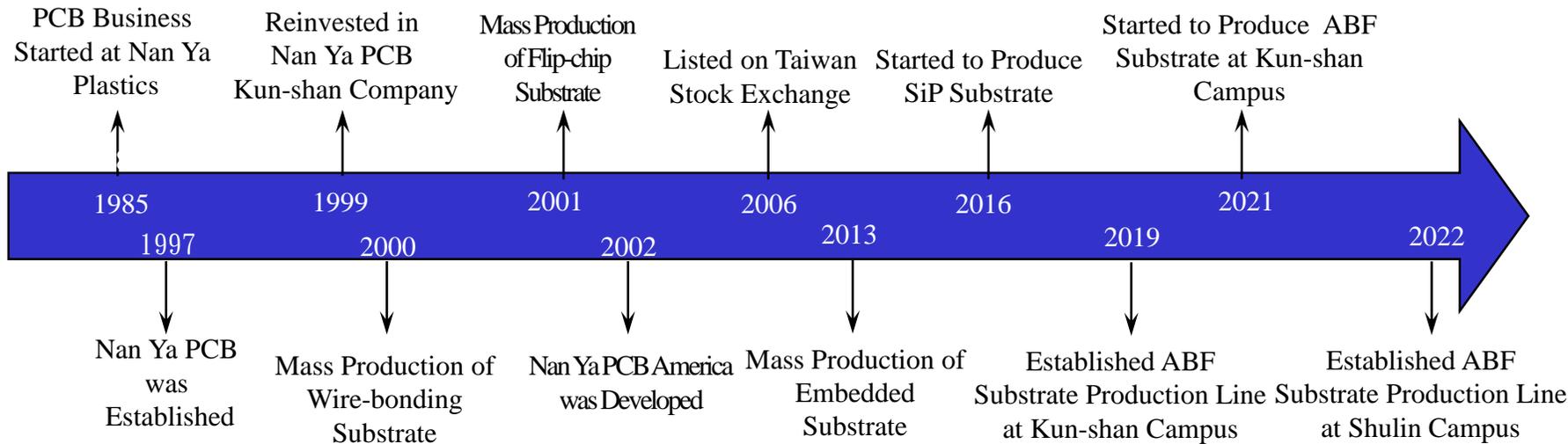
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- **Subsidiary Company of Nan Ya Plastics Corp.**
- **Manufacture and Sell IC Substrates and PCBs**
- **2025 Consolidated Revenues: NTD 40.2 Billion**
- **Market Value: NTD 155.73 Billion(December 31<sup>th</sup> 2025)**
- **Production Locations : Taiwan and China**



# Company Profile

## Milestone



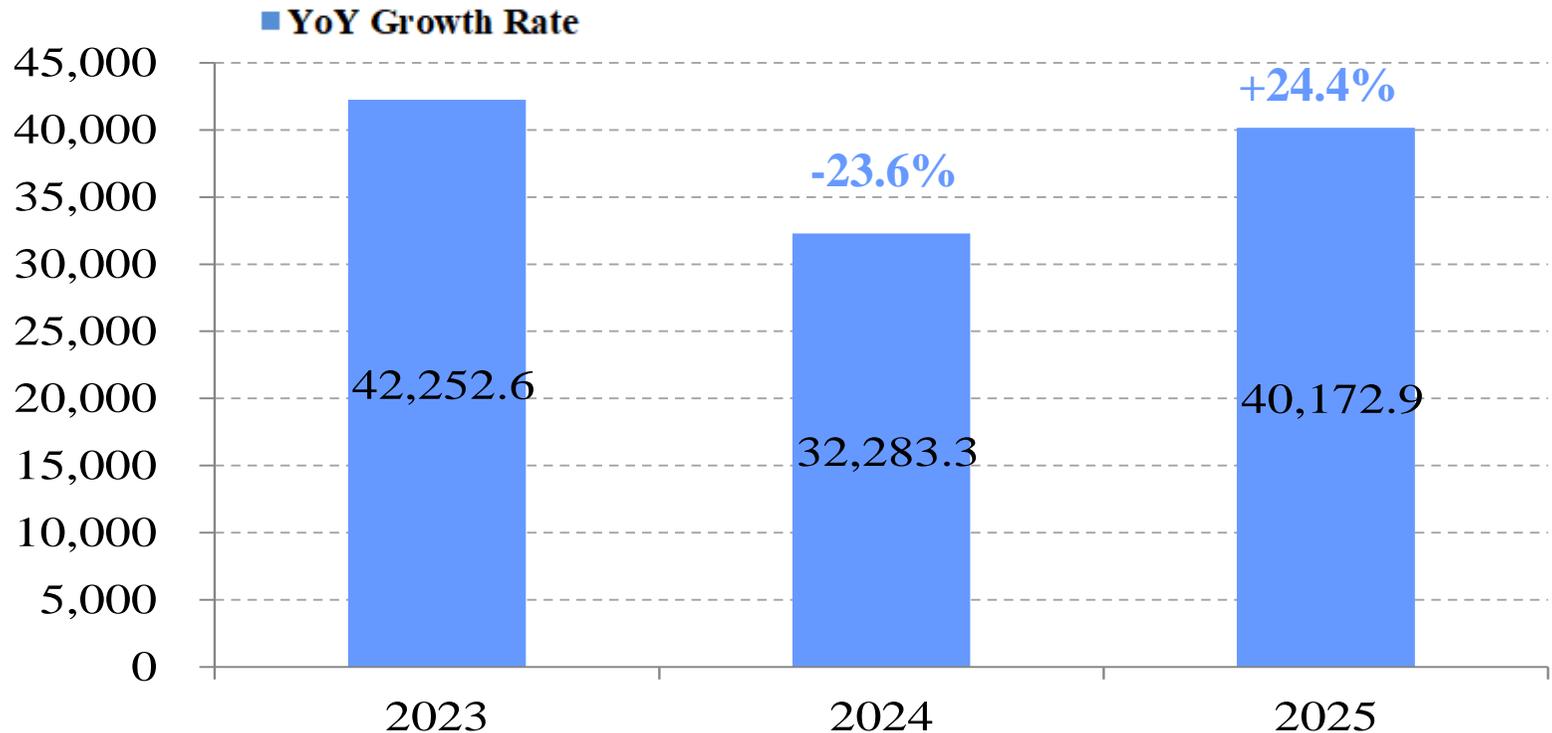
- 1985 : PCB business unit was formed at Nan Ya Plastics Corp. and started manufacturing PCBs
- 1997 : Approved by the Board of Nan Ya Plastics, Nan Ya PCB Corp. was established via reinvestment
- 1999 : Reinvested Nan Ya PCB Kun-shan Company with capital of USD29.8 million
- **2000 : Started manufacturing wire-bonding substrates**
- **2001 : Upgraded technologies and produced flip-chip substrates**
- 2002 : Established Nan Ya PCB America Corp.
- 2006 : Listed on Taiwan Stock Exchange with ticker 8046 TT
- 2013 : Upgraded technologies and produced Embedded substrates
- 2016 : Started to produce System in Package (SiP) substrates
- 2019 : In response to market demand, Nan Ya PCB Corp. started to build ABF substrate production line at Kun-shan Campus
- **2021 : Kun-shan Campus started to manufacture ABF substrates**
- **2022 : Shulin Campus started to manufacture ABF substrates**



# Financial Status

## Consolidated Revenues(IFRS) in Last 3 Years

NTD Million



- **Revenues in 2024 were 23.6% lower than those in 2023:**

Due to ongoing inventory correction in telecom, revenues in 2024 were lower than those in 2023.

- **Revenues in 2025 were 24.4% greater than those in 2024:**

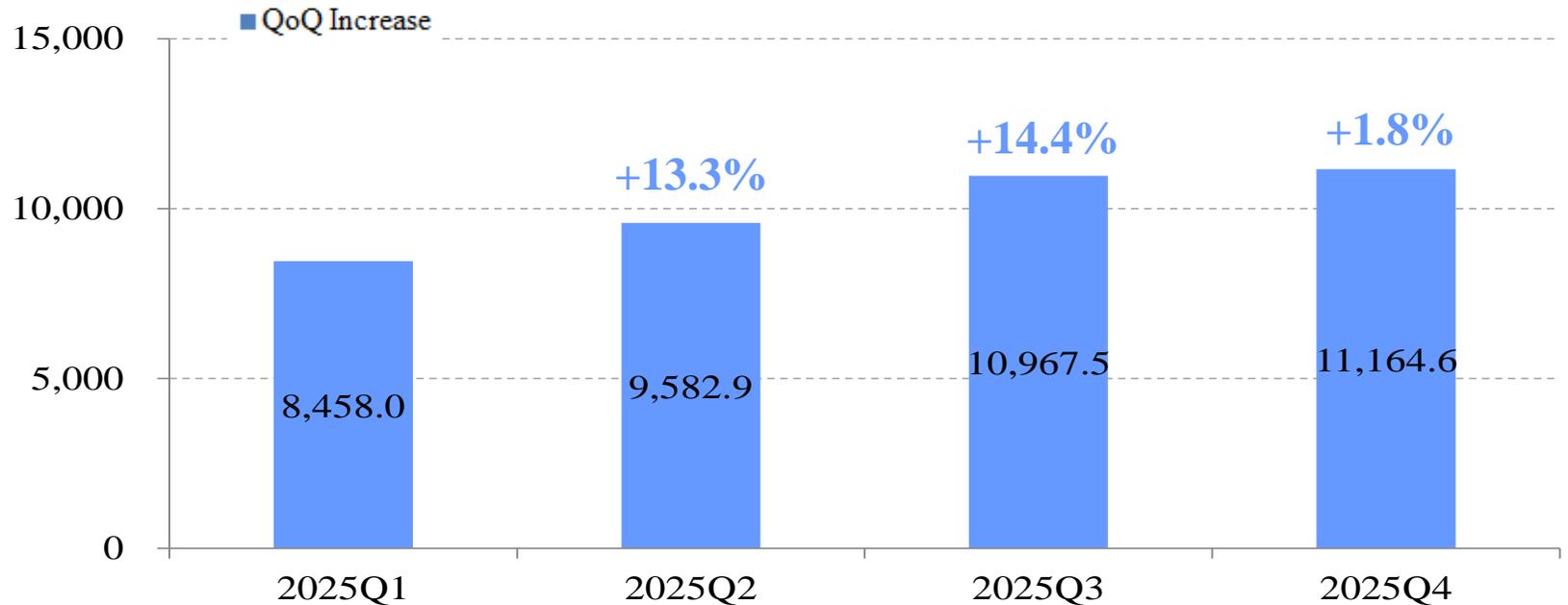
Driven by increased demand for high-end IC substrates and high value-added application substrates for high-end servers, 800G switches, and enterprise-grade solid-state drives, revenue in 2025 increased compared to 2024.



# Financial Status

## Quarterly Consolidated Revenues(IFRS) in a Year

NTD Million

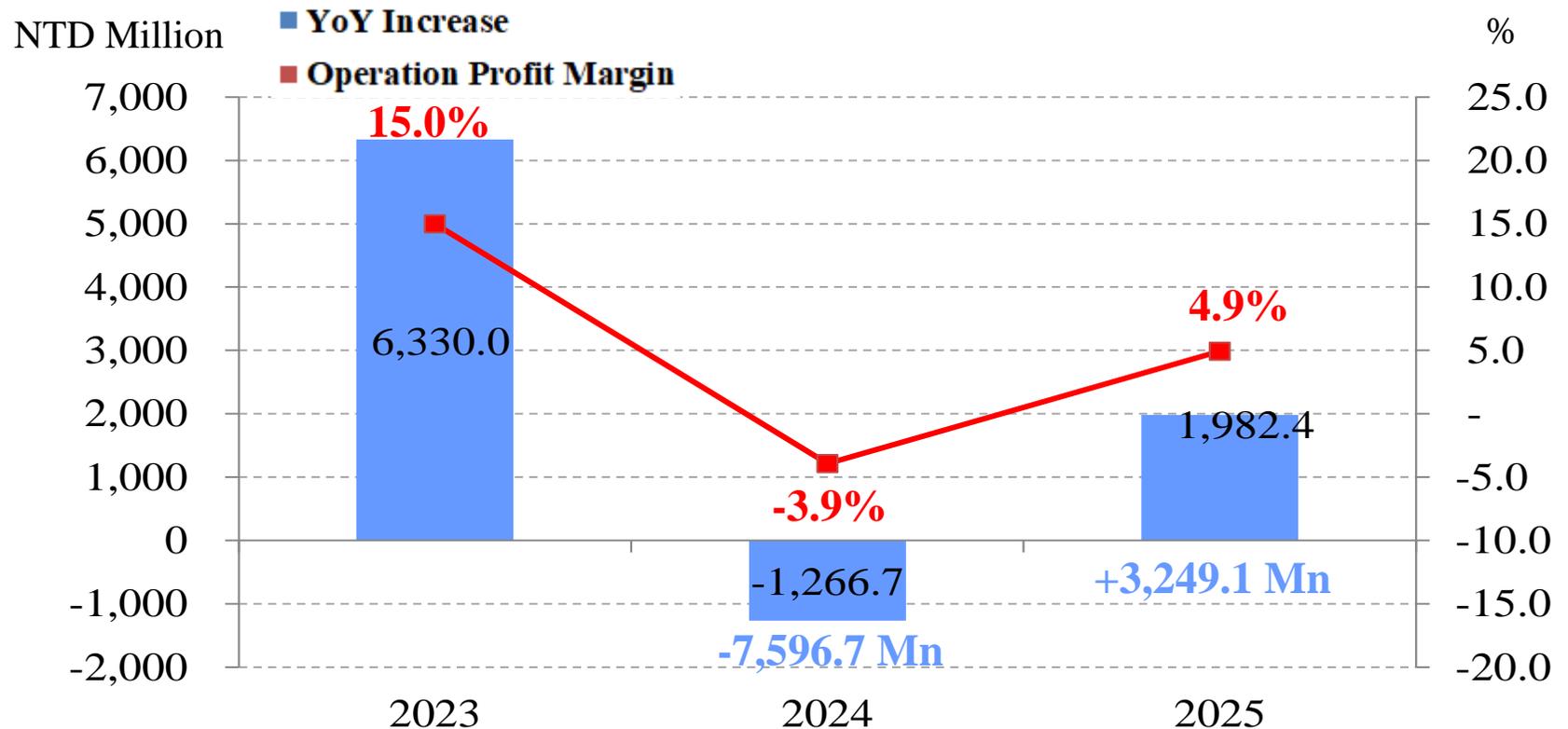


- **Revenues in 25Q2 were 13.3% greater than those in 25Q1:**  
Stronger demand for cloud and edge computing products led to a 25Q2 revenue increase over 25Q1.
- **Revenues in 25Q3 were 14.4% greater than those in 25Q2:**  
Solid growth in cloud application products and a recovery in memory demand led to a further increase in revenue of 25Q3.
- **Revenues in 25Q4 were 1.8% greater than those in 25Q3:**  
Driven by increased demand for high-end servers and switches, revenue in the fourth quarter increased compared to the third quarter.



# Financial Status

## Operation Profits(Losses) in Last 3 Years

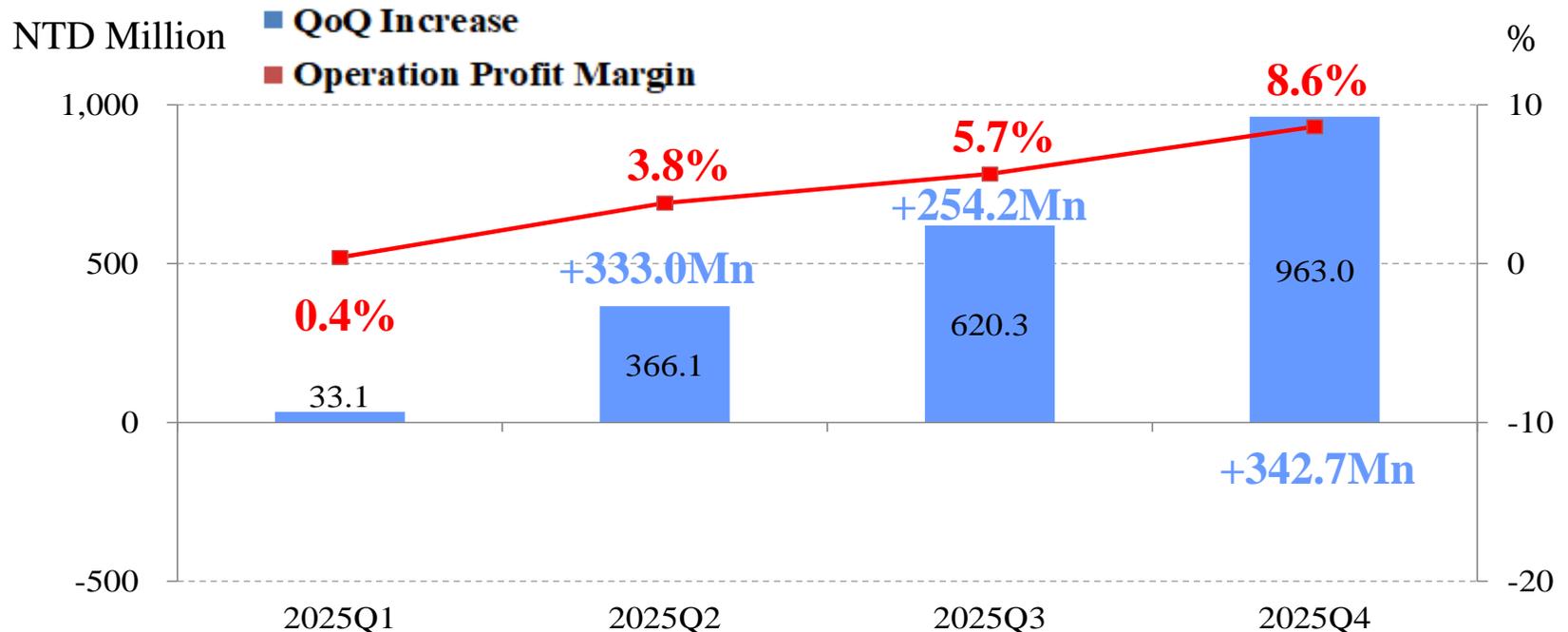


- **Operation profits in 2024 were decreasing NTD 7,596.7 Mn from 2023:**  
Due to weak demand in telecom products, the operating profit decreased.
- **Operation profits in 2025 were increasing NTD 3,249.1 Mn from 2024:**  
An increased sales proportion of high value-added cloud application products, such as servers and high-end switches, resulted in a significant growth in operating profit compared to 2024.



# Financial Status

## Quarterly Operation Profits in a Year

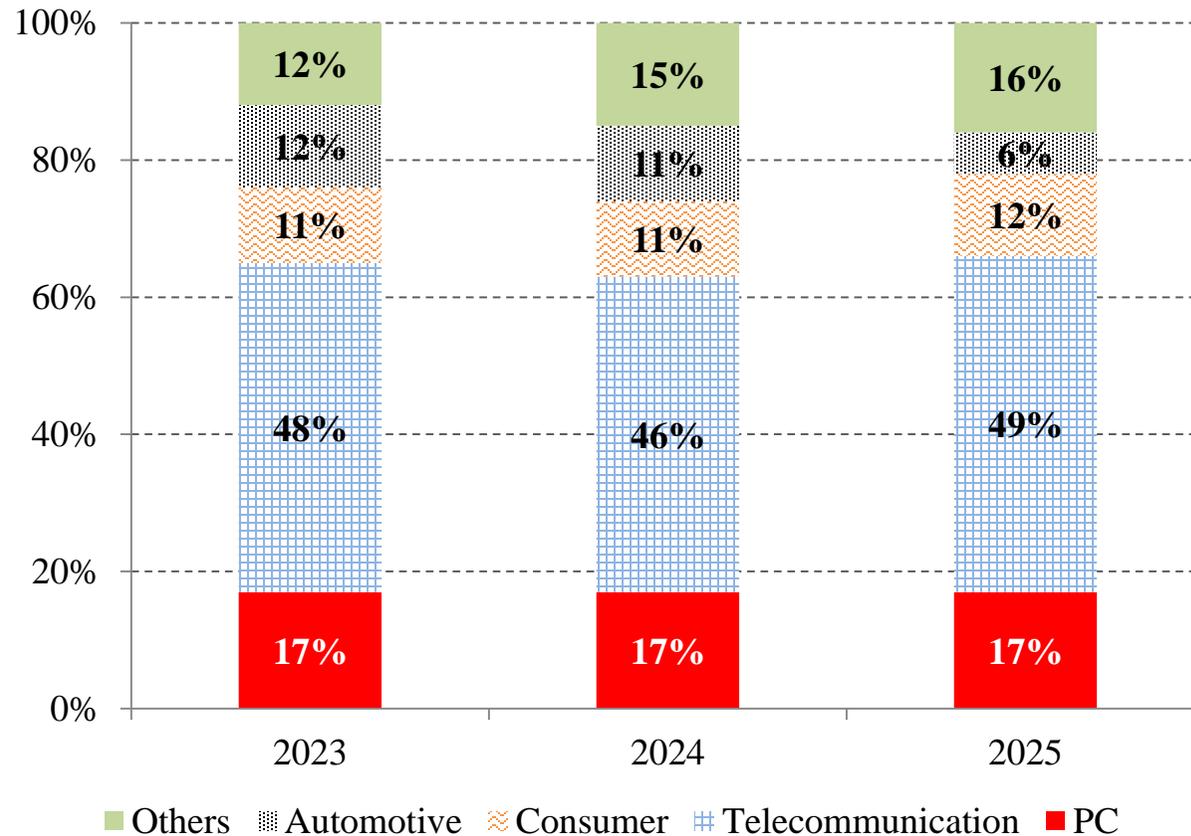


- **Operation profits in 25Q2 were increasing NTD 333.0 Mn from 25Q1:**  
Demand for high-end cloud and edge computing applications increased, further boosting 25Q2 operating profit.
- **Operation profits in 25Q3 were increasing NTD 254.2 Mn from 25Q2:**  
Demand for data center and memory products increased, leading to a rise in operating profit in 25Q3 compared to 25Q.
- **Operation profits in 25Q4 were increasing NTD 342.7 Mn from 25Q3:**  
With an rising demand for high-end servers and switches, operating profit in the fourth quarter increased compared with the third quarter.



# Financial Status

## Revenue Structure(By Applications)

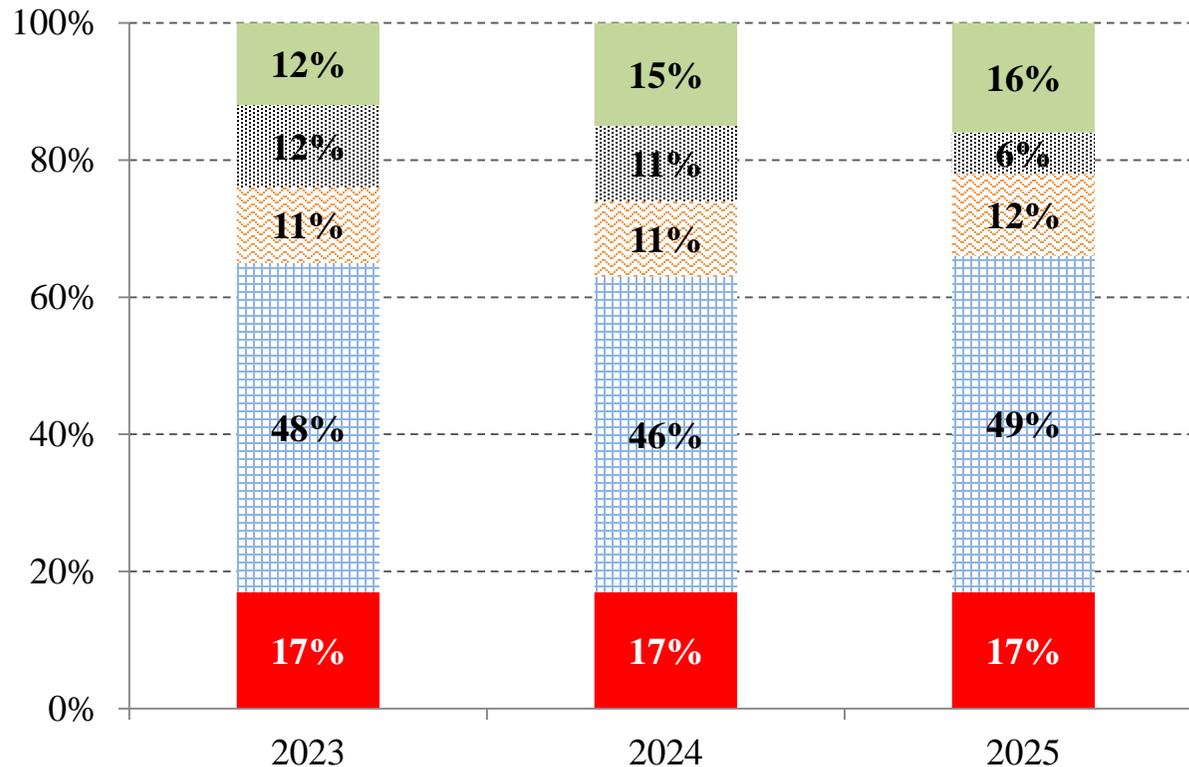


- Due to a decline in personal computer market demand, has resulted in a decrease in revenue contribution in 2025.
- Breakthroughs in large language model technologies and enhanced computing capabilities accelerated the upgrade of AI servers and high-end switches, leading to a higher proportion of networking revenue in 2025.



# Financial Status

## Revenue Structure(By Applications)



■ Others ■ Automotive ■ Consumer ■ Telecommunication ■ PC

- Consumer electronics customers accelerated inventory stocking to mitigate the risk of increased tariffs, resulting in higher related revenue in 2025.
- Intense price competition in the automotive sector, along with supply chain disruptions, has resulted in a decrease in revenue contribution in 2025.
- Driven by rising demand for AI and high-end networking products, the proportion of related revenue continued to increase in 2025.



# Future Product Development

## Continue to Expand High Value Products

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### ■ **ABF Substrate**

As major cloud service providers continue to invest in data center capital expenditures, the Company maintains close collaboration with customers to develop application substrates for next-generation AI servers and application-specific integrated circuit. In response to the high-speed transmission requirements of massive data, we will also develop application substrates for next-generation switches and signal transmission chips, thereby increasing the proportion of high value products.

### ■ **BT Substrate**

In addition to developing application substrates for next-generation mobile devices, including 5G antenna modules, smart glasses, data center storage devices, and solid-state drive controller chips, the Company will collaborate with customers to develop application substrates for next-generation servers and power IC controller chips in response to demand from AI application chips for high power conversion efficiency power management modules, thereby enhancing profitability.

### ■ **Conventional PCB**

Data center servers are driving demand for HDI and multilayer boards. We will develop and mass-produce AI-related products, including server display cards, add-on boards, accelerator cards, and solid-state drive application products. Furthermore, to capitalize on various edge AI opportunities, we will mass-produce high-end PC and LED light bead PCBs to further diversify our product portfolio.



# Operational Strategies in 2026

## Implementing 4 Major Transformations

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- **Product Transformation:** Increase the proportion of high-value and differentiated products, and expand into new applications and markets..
- **Business Transformation:** Develop new materials, technologies, and products to strengthen the Company's capabilities.
- **Digital Transformation:** Leverage digital technologies to enhance AI and digital transformation, achieving intelligent operations.
- **Low-Carbon Transformation:** Expand the use of green energy, commit to energy conservation and carbon reduction, and implement the promotion of a circular economy.



Thank You

